



Material Content Data Sheet



Halogen-Free

Sales Product Name	BSC028N06NSSC	Issued	16. May 2021
MA#	MA005346432		
Package	PG-WSON-8-2	Weight*	99.11 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.172	1.18	1.18	11820	11820
leadframe	inorganic material	phosphorus	7723-14-0	0.011	0.01		115	
	non noble metal	zinc	7440-66-6	0.046	0.05		460	
	non noble metal	iron	7439-89-6	0.912	0.92		9199	
	non noble metal	copper	7440-50-8	37.021	37.37	38.35	373532	383306
wire	noble metal	gold	7440-57-5	0.063	0.06	0.06	639	639
encapsulation	organic material	carbon black	1333-86-4	0.040	0.04		401	
	plastics	epoxy resin	-	1.827	1.84		18432	
	inorganic material	silicondioxide	60676-86-0	17.990	18.15	20.03	181517	200350
leadfinish	non noble metal	tin	7440-31-5	1.365	1.38	1.38	13772	13772
plating	noble metal	silver	7440-22-4	0.839	0.85	0.85	8461	8461
solder	noble metal	silver	7440-22-4	0.034	0.03		339	
	non noble metal	tin	7440-31-5	0.067	0.07		678	
	non noble metal	lead	7439-92-1	1.243	1.25	1.35	12543	13560
heat sink clip	inorganic material	phosphorus	7723-14-0	0.011	0.01		110	
	non noble metal	zinc	7440-66-6	0.044	0.04		442	
	non noble metal	iron	7439-89-6	0.876	0.88		8834	
	non noble metal	copper	7440-50-8	35.552	35.87	36.80	358706	368092
*deviation	< 10%	Sum in total:				100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com